

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

|  |                                    |
|--|------------------------------------|
| <b>SUBMISSION TYPE:</b>  | NEW ASSIGNMENT                     |
| <b>NATURE OF CONVEYANCE:</b>   | ASSIGNMENT                         |
| <b>CONVEYING PARTY DATA</b>  |                                    |
| <b>Name</b>  | <b>Execution Date</b>              |
| Jeng-Yun HSU   | 03/16/2009                         |
| <b>RECEIVING PARTY DATA</b>  |                                    |
| <b>Name:</b>   | Silicon Integrated Systems Corp.   |
| <b>Street Address:</b>   | NO. 180, KUNG TAO 5 RD., SEC. 2    |
| <b>City:</b>   | HSIN CHU CITY                      |
| <b>State/Country:</b>  | TAIWAN                             |
| <b>PROPERTY NUMBERS Total: 1</b>   |                                    |
| <b>Property Type</b>   | <b>Number</b>                      |
| <b>Application Number:</b>   | 12411155                           |
| <b>CORRESPONDENCE DATA</b>   |                                    |
| <b>Fax Number:</b>   | (703)621-7155                      |
| <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> |                                    |
| <b>Phone:</b>  | 7036217140                         |
| <b>Email:</b>  | fec@mg-ip.com                      |
| <b>Correspondent Name:</b>   | Muncy, Geissler, Olds, & Lowe PLLC |
| <b>Address Line 1:</b>   | PO Box 1364                        |
| <b>Address Line 4:</b>   | Fairfax, VIRGINIA 22038            |
| <b>ATTORNEY DOCKET NUMBER:</b>   | 3722/0603PUS1                      |
| <b>NAME OF SUBMITTER:</b>  | Joe McKinney Muncy                 |
| <b>Total Attachments: 1</b><br>source=2009-03-25-Assignment#page1.tif                |                                    |

OP \$40.00 12411155

# MUNCY, GEISSLER, OLDS & LOWE, PLLC

## UNITED STATES PATENT RIGHTS, OR UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

### ASSIGNMENT

For good and valuable consideration, receipt of which hereby acknowledged,

I/We,

(a) JENG-YUN HSU

residing at

(a) 7F-2, NO. 28, LANE 59, CHIEN KUNG 1 RD., HSIN CHU CITY, TAIWAN, R.O.C.

assign and transfer to: **Silicon Integrated Systems Corp.**

a corporation organized under the law of Taiwan and having a place of business at : **NO. 180, KUNG TAO 5 RD., SEC. 2, HSIN CHU CITY, TAIWAN, R.O.C.**

its successors and assigns, my entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled: **APPARATUS AND METHOD FOR LOW ANGLE INTERPOLATION**

including divisions, reissues, continuations and extensions thereof, and all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States application, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in United States; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

|                      |                       |             |             |
|----------------------|-----------------------|-------------|-------------|
| Joint Inventor (a)   | JENG-YUN HSU          |             |             |
| Inventor's Signature | Jeng Yun Hsu          | Date        | MAR 16 2009 |
| Residence            | HSIN CHU CITY, TAIWAN | Citizenship | R.O.C.      |

|                      |  |             |  |
|----------------------|--|-------------|--|
| Joint Inventor (b)   |  |             |  |
| Inventor's Signature |  | Date        |  |
| Residence            |  | Citizenship |  |

|                      |  |             |  |
|----------------------|--|-------------|--|
| Joint Inventor (c)   |  |             |  |
| Inventor's Signature |  | Date        |  |
| Residence            |  | Citizenship |  |

|                      |  |             |  |
|----------------------|--|-------------|--|
| Joint Inventor (d)   |  |             |  |
| Inventor's Signature |  | Date        |  |
| Residence            |  | Citizenship |  |

08P141-US